2026 VLSI SYMPOSIUM

2026 IEEE SYMPOSIUM ON VLSI TECHNOLOGY AND CIRCUITS

HILTON HAWAIIAN VILLAGE
HONOLULU, HAWAII | JUNE 14-18, 2026

ADVANCING THE AI FRONTIER
through VLSI Innovation

SECOND CALL FOR PAPERS

Paper Submission Deadline: 23:59 PST Monday, January 26, 2026
www.vlsisymposium.org

Symposium Scope

The Symposium calls for papers in the following areas:

- Advanced CMOS Platforms, Interconnect and Backside Power Delivery Network (BSPDN) Technologies
- Advanced packaging, Chiplet and Heterogeneous Integration Technologies, including 2.5D and 3D
- Analog and Mixed-Signal Circuits
- Beyond CMOS Devices That Utilize New Physics Including Spin, Optical and Quantum Computing
- Biomedical devices, circuits, and systems
- Computing/Processing in Memory
- Data converters
- Device physics, Characterization, Modeling and Reliability
- Devices and Accelerators for ML/DL and New Compute
- Digital Circuits, Hardware Security, Signal Integrity, IOs
- DTCO and Design Enablement
- Frequency Generation and Clocking Circuits
- Memory Technologies, Devices, Circuits, and Architectures
- Power Management Devices and Circuits
- Processes and Materials for CMOS Scaling and New Devices
- Processors and SoCs
- Sensors, Imagers, IoT, MEMS, Display Circuits
- Wireless and RF Devices Circuits and Systems
- Wireline and Optical Transceivers, Optical Interconnects and Processors

Further Information

The Symposium website is the central resource for additional information, including details on paper submissions and Best Student Paper eligibility.

Highlights

The Symposium will be a fully in-person event with live sessions at the Hilton Hawaiian Village, Honolulu, Hawaii, to foster networking, with on-demand access to technical sessions available one week following the Symposium. The 5-day event will include:

- **Plenary Sessions**
- **Technical Sessions**
- **Demo Session for outstanding papers**
- **Full-Day Short Courses on key VLSI topics**
- **Evening Panels**
- **Workshops**
- **SSCS/EDS Women in Engineering and Young Professionals Events**
- **Hawaiian Luau celebration**

Paper Submission

Prospective authors must submit paper abstracts in the **three-page paper format** according to the Symposium website: www.vlsisymposium.org. Accepted papers will be published as submitted with no revisions permitted. Authors must follow detailed instructions provided in the "Authors" section of the website, including the Authors' Guide and Pre-publication Policy. **Students are encouraged to apply for the prestigious Best Student Paper Award. Extended versions of outstanding papers will be invited for publication in the IEEE Transaction on Electron Devices, IEEE Journal of Solid-State Circuits, and IEEE Solid-State Circuits Letters.**

Call for Workshops

The Symposium provides valuable opportunities for volunteers to apply to organize and host short workshops at the Symposium.

Detailed information is available here: www.vlsisymposium.org.

IEEE ELECTRON DEVICES SOCIETY SSCS EiC in

Symposium Chairs:
Vijay Narayanan, IBM T.J. Watson Research Center
Ron Kapusta, Analog Devices

Symposium Co-Chairs:
Kazuhiko Endo, Tohoku University
Sugako Otani, Renesas Electronics Corporation

Program Chairs:
Benjamin Colombeau, Applied Materials
John Wuu, Advanced Micro Devices

Program co-chairs:
Masaharu Kobayashi, The University of Tokyo
Makoto Takamiya, The University of Tokyo

(North America and Europe) :
Canfield Event Management
vlsi@vlsisymposium.org, +1-972-521-9902

(Asia and Japan)
JTB Communication Design
vlsisymp@jtbcom.co.jp, +81-3-5657-0777